PICK-UP APPARATUS AND METHOD FOR SEMICONDUCTOR CHIPS

ABSTRACT

A method for sequentially picking up non-faulty chips arranged on an X-Y table. A plurality of chips (10) disposed in an aligned arrangement is viewed by a camera (2) in a field of view of the camera (2) to provide an image data for enabling a preceding image recognition for a chip (10) simultaneously with a pick-up operation for another chip (10). Three chip (10) locations adjacent to each other along a moving direction of the camera (2) are encompassed by the field of view. During the time period for a pick-up operation of a particular chip (10) located at the center of the field of view, a preceding recognition is conducted for the succeeding chip (10) located adjacent to and ahead of the particular chip (10) on the basis of image data, thereby examining whether the succeeding chip (10) is faulty or non-faulty during the pick-up operation for the particular chip (10).

Fig. 3